

Claims

What is claimed is:

1. A mask for use in printing solder on a plurality of terminals formed on a substrate so as to correspond to a plurality of terminals of an IC package, wherein said mask has openings through which the solder is applied, and the openings are larger than the terminals on the substrate.
2. A mask according to claim 1, wherein the substrate is subjected to solder reflow.
3. A mask according to claim 1, wherein a conductive region is formed between at least one pair among the plurality of substrate terminals, and
the openings extend between one terminal of the pair of the substrate terminals and the conductive region.
4. A mask according to claim 3, wherein the conductive region is a wiring line extending from the substrate terminals.
5. A wiring board production method comprising:
applying solder through openings in a mask to each of a plurality of substrate terminals formed on a substrate so as to correspond to a plurality of terminals of an IC package,
wherein an area of the solder applied to each of the substrate terminals is larger than that of the substrate terminal.

6. A wiring board production method according to claim 5, further including a solder reflow step of causing the solder applied to the substrate to be melted.

7. A wiring board production method according to claim 5, wherein a conductive region is formed between at least one pair of the substrate terminals, and

in the step of applying solder, the solder is applied to the substrate so that one of the substrate terminals is entirely covered with the solder and at least a portion of a width of the conductive region is covered with the solder.

8. A wiring board production method according to claim 7, wherein the conductive region is a wiring line extending from the substrate terminals.

9. A wiring board which is produced by the wiring board production method according to claim 5.

10. An electrooptical apparatus production method including a step of implementing the wiring board production method according to claim 5.

11. An electrooptical apparatus which is produced by the electrooptical apparatus production method according to claim 10.

12. An electronic device production method including a step of implementing the electrooptical apparatus production method according to claim 10.

13. An electronic device which is produced by the electronic device production method according to claim 12.